### PRODUCT / PROCESS CHANGE NOTIFICATION

| 1. PCN basic data    |            |  |
|----------------------|------------|--|
| 1.1 Company          | <b>577</b> | STMicroelectronics International N.V   |
| 1.2 PCN No.          |            | ADG/18/11016   |
| 1.3 Title of PCN     |            | PowerFLAT™ 8x8 HV New Die Attach process & material from Power Glue to Solder Paste - ASE-WEIHAI (China) |
| 1.4 Product Category |            | Power MOSFET   |
| 1.5 Issue date       |            | 2018-07-25   |

| 2. PCN Team               |                            |  |
|---------------------------|----------------------------|--|
| 2.1 Contact supplier      |                            |  |
| 2.1.1 Name                | MARCELI SMIALKOWSKI        |  |
| 2.1.2 Phone               | +44 1628896277             |  |
| 2.1.3 Email               | marceli.smialkowski@st.com |  |
| 2.2 Change responsibility |                            |  |
| 2.2.1 Product Manager     | Maurizio GIUDICE           |  |
| 2.1.2 Marketing Manager   | Paolo PETRALI              |  |
| 2.1.3 Quality Manager     | Vincenzo MILITANO          |  |

| 3. Change    |  |                            |  |
|--------------|--|----------------------------|--|
| 3.1 Category | 3.2 Type of change   | 3.3 Manufacturing Location |  |
| Materials    | New Indirect material part number (same supplier or different supplier): Solder ball composition | ASE-WEIHAI (China)         |  |

| 4. Description of change  |            |  |  |
|---|------------|--|--|
|   | Old        | New  |  |
| 4.1 Description   |            | Selected products in PowerFLAT <sup>TM</sup> 8x8 HV, are manufactured by ASE-WEIHAI (China) Subcontractor with Solder Paste in the Die Attach Process. |  |
| 4.2 Anticipated Impact on form,fit, function, quality, reliability or processability? | no impacts |  |  |

| 5. Reason / motivation for change |                     |
|-----------------------------------|---------------------|
| 5.1 Motivation                    | Improve Quality     |
| 5.2 Customer Benefit              | QUALITY IMPROVEMENT |

| 6. Marking of parts / traceability of change |   |  |
|--|---|--|
|  | will be identified by the additional info "P" marked on the package and internal code reported in the Box Label of the packing. |  |

| 7. Timing / schedule                |              |  |
|-------------------------------------|--------------|--|
| 7.1 Date of qualification results   | 2018-07-18   |  |
| 7.2 Intended start of delivery      | 2018-10-28   |  |
| 7.3 Qualification sample available? | Upon Request |  |

| 8. Qualification / Validation                      |                    |               |            |
|--|--------------------|---------------|------------|
| 8.1 Description                                    | 11016 Rel14-18.pdf |               |            |
| 8.2 Qualification report and qualification results |                    | Issue<br>Date | 2018-07-25 |

## 9. Attachments (additional documentations)

11016 Public product.pdf 11016 PowerFLAT™ 8x8 HV New Die Attach process & material from Power Glue to Solder Paste.pdf 11016 Rel14-18.pdf

| 10. Affected parts      |                         |                          |
|-------------------------|-------------------------|--------------------------|
| 10. 1 Current           |                         | 10.2 New (if applicable) |
| 10.1.1 Customer Part No | 10.1.2 Supplier Part No | 10.1.2 Supplier Part No  |
|                         | STL33N60DM2             |                          |
|                         | STL57N65M5              |                          |

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# **Public Products List**

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PCN Title: PowerFLAT™ 8x8 HV New Die Attach process & material from Power Glue to Solder Paste - ASE-WEIHAI (China)

PCN Reference: ADG/18/11016

Subject: Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

| STL45N65M5  | STL57N65M5 | STL38N65M5 |
|-------------|------------|------------|
| STL33N60M2  | STL36N55M5 | STL26NM60N |
| STL33N60DM2 | STL33N65M2 |            |

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